

Amendments to the Claims:

Claims 1, 9, and 17 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A laser-markable structure for marking a semiconductor device comprising:
a tape comprising a flexible film material having a coefficient of thermal expansion substantially similar to the semiconductor device; and
a multilayer adhesive including:
a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components, the electromagnetic radiation-curable components providing a laser-markable surface upon exposure to an electromagnetic radiation source by curing and bonding to at least a portion of a semiconductor device when laser marking a semiconductor device; and
a second adhesive layer disposed between the tape and the first outermost adhesive layer, the second adhesive layer comprising a mixture of electromagnetic radiation-curable components upon exposing to radiation the second adhesive layer performs at least one property of the adhesive for curing onto portions of the first outermost adhesive layer and for losing adhesive properties for facilitating peeling of the flexible film material when laser marking a semiconductor device.
2. (Canceled)
3. (Previously Presented) The laser-markable structure of claim 1, wherein the at least a portion of the surface of a bare semiconductor device has grinding marks therein.

4. (Previously Presented) The laser-markable structure of claim 1, wherein the first outermost adhesive layer comprises a permanently attached layer to at least a portion of the surface of the bare semiconductor device when the radiation-curable components are in a cured state.

5. (Canceled)

6. (Previously Presented) The laser-markable structure of claim 4, wherein the laser-markable surface includes a substantially homogenous surface disposed over the at least a portion of the surface of the bare semiconductor die.

7. (Canceled)

8. (Previously Presented) The laser-markable structure of claim 1, wherein the tape comprises a flexible film material having translucent properties.

9. (Currently Amended) A tape for use in the laser marking of a semiconductor device comprising:

a flexible film material having a coefficient of thermal expansion substantially similar to the semiconductor device; and

a multilayer adhesive including:

a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components for providing a mark on a laser-markable surface upon exposure thereof to electromagnetic radiation by curing and bonding to at least a portion of a semiconductor device when laser marking a semiconductor device; and

a second adhesive layer disposed between the flexible film material and the first outermost adhesive layer, the second adhesive layer comprising a mixture of

electromagnetic radiation-curable components upon exposing to radiation the second adhesive layer performs at least one property of the adhesive for curing onto portions of the first outermost adhesive layer and for losing adhesive properties for facilitating peeling of the flexible film material when laser marking a semiconductor device.

10. (Canceled)

11. (Previously Presented) The tape of claim 9, wherein the portion of the surface of the semiconductor device has grinding marks therein.

12. (Previously Presented) The tape of claim 9, wherein the first outermost adhesive layer is permanently attached to the at least a portion of the surface of the bare semiconductor die when the radiation-curable components are in a cured state.

13. (Canceled)

14. (Previously Presented) The tape of claim 12, wherein the laser-markable surface comprises a substantially homogenous surface disposed over the at least a portion of the surface of the bare semiconductor die suitable for providing a mark by laser marking.

15 (Canceled)

16. (Previously Presented) The tape of claim 9, wherein the flexible film material comprises a flexible film material having translucent properties.

17. (Currently Amended) A tape for use in the marking of a semiconductor device comprising:
film material having a coefficient of thermal expansion substantially similar to the semiconductor device; and
at least two layers of adhesive including:

a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components for providing a mark on a surface upon exposure thereof to electromagnetic radiation by curing and bonding to at least a portion of a semiconductor device when laser marking a semiconductor device; and
a second adhesive layer disposed between the film material and the first outermost adhesive layer, the second adhesive layer comprising a mixture of electromagnetic radiation-curable components upon exposing to radiation the second adhesive layer performs at least one property of the adhesive for curing onto portions of the first outermost adhesive layer and losing adhesive properties for facilitating peeling of the flexible film material when laser marking a semiconductor device.

18. (Canceled)

19. (Previously Presented) The tape of claim 17, wherein the portion of the surface of the semiconductor device has grinding marks therein.

20. (Previously Presented) The tape of claim 17, wherein the first outermost adhesive layer is permanently attached to the at least a portion of the surface of the bare semiconductor die when the radiation-curable components are in a cured state.

21. (Canceled)

22. (Previously Presented) The tape of claim 20, wherein the electromagnetic radiation-curable components form a substantially homogenous surface upon exposure to an electromagnetic radiation source, the substantially homogenous surface being disposed over the at least the portion of the surface of a bare semiconductor die, the substantially homogenous surface being suitable for laser marking for forming a mark on the surface of the bare semiconductor die.

23. (Canceled)

24. (Previously Presented) The tape of claim 17, wherein the film material comprises a film material having translucent properties.